

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 1038 | "438"/\$.ccls. and (die ic chip) with (thin\$4 grind\$3 polish\$3) and (substrate board carrier interposer) with (thin\$4 grind\$3 polish\$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/22 20:15 |
| L2 | 181 | "29"/\$.ccls. and (die ic chip) with (thin\$4 grind\$3 polish\$3) and (substrate board carrier interposer) with (thin\$4 grind\$3 polish\$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/22 20:22 |
| L3 | 2058 | "257"/\$.ccls. and (die ic chip) with (thin\$4 grind\$3 polish\$3) and (substrate board carrier interposer) with (thin\$4 grind\$3 polish\$3) and first adj3 (support substrate board carrier interposer) and second adj3 (support substrate board carrier interposer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/22 20:24 |